REVISIONS									
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED						
A	Add device types 02 and 03. Add vendor CAGE 61772 for device types 02 and 03. Delete vendor CAGE 61772 for device type 01. Add vendor CAGE 75569 for device types 02 and 03. Technical and editorial changes throughout.	92-03-06	W.O.Fje						

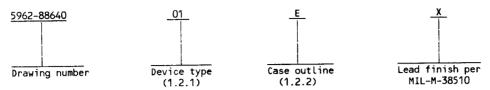
THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

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PMIC N/A PREPARED BY Jeffery Tunstall					DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444															
STANDARDIZED MILITARY			CHECKED BY Ray Monnin				MICROCIRCUITS, DIGITAL, FAST CMOS													
DRAWING THIS DRAWING IS AVAILABLE			APPROVED BY D. R. Cool				SYNCHRONOUS PRESETTABLE BINARY, COUNTER, TTL COMPATIBLE, MONOLITHIC							IC						
FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE				DRAWING APPROVAL DATE 88-09-30				SILICON												
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DESC FORM 193

1. SCOPE

- This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance w MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	Generic number	<u>Circuit function</u>
01 <u>1</u> /	54FCT161	Presettable binary counter, synchronous, TTL compatible
02	54FCT161	Presettable binary counter, synchronous, TTL compatible
03	54FCT161A	Presettable binary counter, synchronous, TTL compatible

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in appendix C of MIL-M-38510, and as follows:

Case outline Outline letter

D-2 (16-lead, .840" x .310" x .200"), dual-in-line package Ε F-5 (16-lead, .440" x .285" x .085"), flat package C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package 2

1.3 Absolute maximum ratings. 2/

-0.5 V dc to +7.0 V dc -0.5 V dc to V_{CC} + 0.5 V dc 3/ -0.5 V dc to V_{CC} + 0.5 V dc 3/ -20 mA -50 mA ±100 mA 500 mW See MIL-M-38510, appendix C -65°C to +150°C Junction temperature (T,)--------+175°C +300°C Lead temperature (soldering, 10 seconds) - - - - - -

All voltage referenced to GND.

2/ All voltage referenced to GND. $\overline{3}/$ For V_{CC} > 6.5 V dc, the upper bound is limited to V_{CC}. $\overline{4}/$ Must withstand the added P_D due to short circuit test e.g., I_{OS}.

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 $[\]overline{1/}$ Due to internal noise problems, device type 01 does not meet the minimum V_{IH} threshold limit characteristic of the FCT family or the limits specified on this drawing. This device type is no longer available for acquisition.

1.4 Recommended operating conditions. +4.5 V dc to +5.5 V dc

-55°C to +125°C

5.5 ns 4.5 ns

Minimum setup time, high or low (PE to CP) (t_{s2}): 13.5 ns 11 5 ns Minimum setup time, high or low (CEP, CET to CP) (t_{s3}):

13.0 ns 11.0 ns 2.0 ns 1.5 ns

Minimum hold time, high or low $(P_1 \text{ to CP})$ $(t_{h1}) - - -$ Minimum hold time, high or low (PE to CP) $(t_{h2}) - - - -$ Minimum hold time, high or low (CEP, CET to CP) $(t_{h3}) -$ Minimum CP pulse width, high, low (load) (t_{w1}) : 0.0 ns 5.0 ns 4 0 ns

Minimum CP pulse width, high, low (count) (tw2): 8 0 ns 7.0 ns

5.0 ns 4.0 ns

2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

5.0 ns

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

For dynamic operation of device type 01, a V_{IH} level between 2.0 V and 3.0 V may be recognized by this device as a high logic level input. For static operation of device type 01, a $V_{IH} \ge 2.0$ V will be recognized by these devices as a high logic level input. Users are cautioned to verify that this change will not affect their system.

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REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connection(s). The terminal connection(s) shall be as specified on figure 1 herein.
 - 3.2.2 <u>Truth table</u>. The truth table shall be as specified on figure 2 herein.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3 herein.
 - 3.2.4 Counting sequence. The counting sequence shall be as specified on figure 4.
 - 3.2.5 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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Test	Symbol	Con-	ditions ~ < +125°C	Device type	Group A subgroups	Limits		Unit
		v _{cc} = 5	c ≤ +125°C .0 v dc ±10%			Min	Max	-
High level output voltage	V _{OH} 1/	V _{CC} = 4.5 V V _{IL} = 0.8 V V _{IH} = 2.0 V	I _{OH} = -300 μA	ALL	1, 2, 3	4.3		Ů v
		IH - 2.0	I _{OH} = -12 mA	ALL	1, 2, 3	2.4		
Low level output voltage	v _{oL} 1/	V _{CC} = 4.5 V V _{IL} = 0.8 V V _{IH} = 2.0 V	$I_{OL} = 300 \mu A$	All	1, 2, 3		0.2	v
		TH 2.5	I _{OH} = 32 mA	ALL	1, 2, 3		0.5	
Input clamp voltage	v _{IK}	v _{cc} = 4.5 v,	I _N = -18 mA	All	1, 2, 3		-1.2	V
High level input	IIH	v _{cc} = 5.5 v,	v _{IN} = 5.5 V	All	1, 2, 3		5.0	μ A
Low level input	IIL	v _{cc} = 5.5 v,	V _{IN} = GND	All	1, 2, 3		-5.0	
Short circuit output current	Ios	V _{CC} = 5.5 V V _{OUT} = GND	<u>3</u> /	ALL	1, 2, 3	-60		mA
Quiesecent power supply current (CMOS inputs)	1 _{CCQ}	V _{CC} = 5.5 V, V _{IN} ≥ 5.3 V,	$V_{IN} \leq 0.2 \text{ V or } f_{I} = 0 \text{ MHz}$	All	1, 2, 3		1.5	mA
Quiesecent power supply current (TTL inputs)	ΔI _{CC}	v _{cc} = 5.5 v,	v _{IN} = 3.4 v	All	1, 2, 3		2.0	
Dynamic power supply current	IccD	outputs open	$\frac{V}{MR} \underbrace{IN}_{V} \geq 5.3 \text{ V or}$ $\frac{V}{MR} \underbrace{IN}_{V} \geq \frac{C}{V}$, one bit toggling, uty cycle $\underline{5}/$	All			0.25	mA/MH
Total power supply current <u>6</u> /	Icc	outputs open $V_{IN} \leq 0.2 V$,	fcp = 10 MHz, , $V_{IN} \ge 5.3 V$ or ling at $f_{I} = 5 MHz$, uty cycle	ALL	1, 2, 3		4.0	mA
		oŭťputs open	fcp = 10 MHz, , V _{IN} = 3.4 V or ne Dit toggling z,	All	1, 2, 3		6.0	

See footnotes at end of table.

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		TABLE I. Electrical performance	characteristics	- Continued.			
Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C	Device type	Group A subgroups	Limi	ts	Unit
	<u> </u>	-55°C < T _C < +125°C V _{CC} = 5.0 V dc ±10%			Min	Max	<u> </u>
Functional tests	7/		ALL	7, 8			
Input capacitance	CIN	See 4.3.1c	ALL	4		10	 pf
Output capacitance	COUT	See 4.3.1c	All	4		12	pF
Propagation delay	t _{PLH1}	$C_L = 50 \text{ pf minimum}$ $R_1 = 500\Omega \text{ 8}/$	01,02	9,10,11	2.0	11.5	ns
time CP to Qn (PE input high)	PAL!	See figure 5	03	9,10,11	2.0	7.5	
Propagation delay	t _{PLH2}		01,02	9,10,11	2.0	10.0	ns
(PE input low)	PHLZ	_	03	9,10,11	2.0	6.5	
Propagation delay	t _{PLH3}		01,02	9,10,11	2.0	16.5	ns
	FILE		03	9,10,11	2.0	10.8	<u> </u>
Propagation delay	t _{PLH4}		01,02	9,10,11	1.5	9.0	ns
PHLA	PHL4		03	9,10,11	1.5	5.9	
Propagation delay	t _{PHL5}		01,02	9,10,11	2.0	12.5	ns
time rik to it			03	9,10,11	2.0	8.2	
Propaga <u>ti</u> on delay	t _{PHL6}		01,02	9,10,11	2.0	14.0	ns
time MR to Qn			03	9,10,11	2.0	9.1	

^{1/} For dynamic operation of device type 01, a V_{IH} level between 2.0 V and 3.0 V may be recognized by this device as a high logic level input. For static operation of device type 01, a $V_{IH} \ge 2.0$ V will be recognized by this device as a high logic level input. Users are cautioned to verify that this change will not affect their system.

Guaranteed by testing at worst case condition of $V_{CC} = 3$ volts. Not more than one output should be shorted at one time. Duration of the short circuit test should not exceed 1 second.

In accordance with TTL driven input ($V_{IN} = 3.4 \text{ V dc}$); all other outputs at V_{CC} or GND. This parameter is not directly testable, but is derived for use in total power supply calculations.

Where $D_H = Duty$ cycle for TTL inputs high. $N_T = Number of TTL inputs at D_H$. $N_I = Number of TTL inputs at D_H$. $N_I = Number of Inputs at TI$.

7/ Due to internal noise problems, device type 01 cannot meet the threshold limits required in accordance with MIL-STD-883, test method 5004, for the V_{IH} minimum limit (2.0 V) of this technology family. For device types 02 and 03, use a V_{IH} limit of 3.0 V. The V_{IL} limit (0.8 V) remains unchanged. Users are cautioned to verify that this change will not affect their system.

8/ Minimum limits are guaranteed, if not tested, on propagation delays.

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Device types	01,	02, 03
Case outline	E and F	2
Terminal number	Term symb	
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	MR P PO 1 2 3 P D P E M S C C C C C C C C C C C C C C C C C C	NCR CP PP1C P23P CEND PET GNC PET GNC QC C

	PIN description
Terminal symbol	Description
CEP	Count enable parallel input
CET	Count enable trickle input
СР	Clock pulse input (active rising edge)
MR	Asynchronous master reset input (active low)
P ₀₋₃	Parallel data inputs
PE	Parallel enable input (active low)
Q ₀₋₃	Flip-flop outputs

FIGURE 1. <u>Terminal connections</u>.

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MR	PE	CET	CEP	Function
<u> </u>	x	X	х	Reset (clear)
Н	L	X	X	Load (P _n to Q _n) (See note)
H	Н	н	H	Count (increment) (See note)
Н	н	L	X	No change (hold) (See note)
Н	н	х	L	No change (hold) (See note)

H = High voltage level steady-state.
L = Low voltage level steady-state.
X = Irrelevant.

NOTE: Action on the rising clock edge.

FIGURE 2. <u>Truth table</u>.

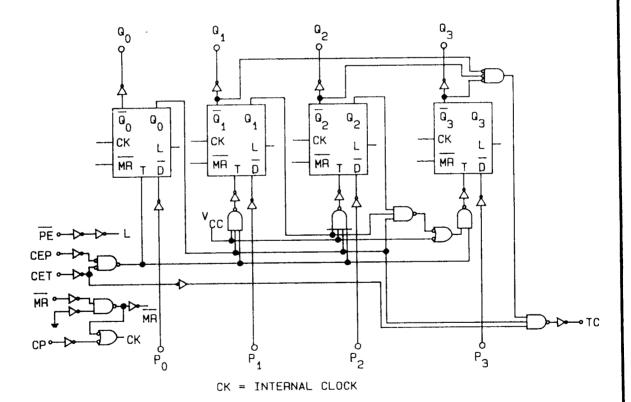
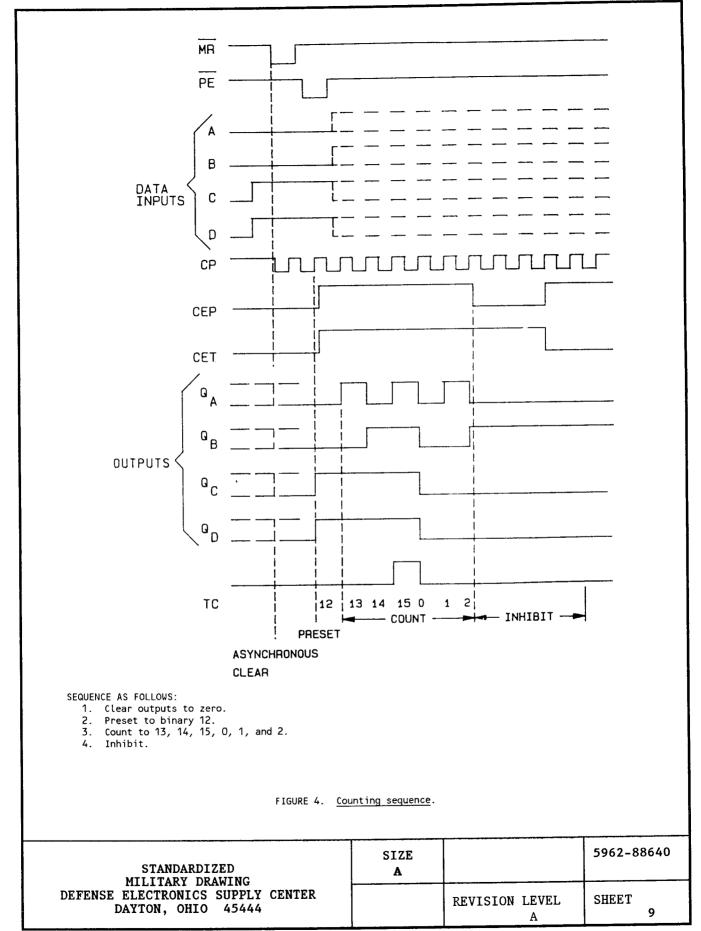
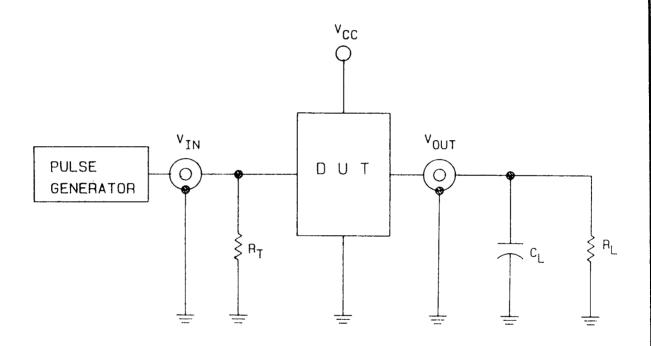


FIGURE 3. Logic diagram.

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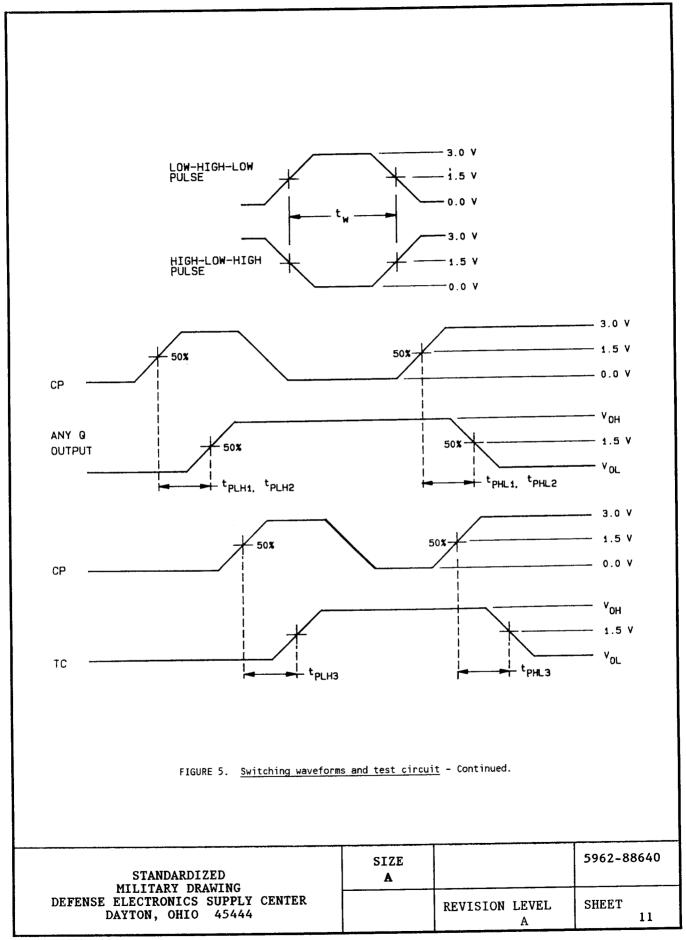




Definitions: $\begin{array}{l} R_L = \text{Load resistor} = 500 \Omega, \\ c_L^* = \text{Load capacitance} = 50 \text{ pF minimum, includes jig and probe capacitance}, \\ R_T^* = \text{Termination should be equal to Z}_{OUT} \text{ of pulse generators}. \end{array}$

FIGURE 5. Switching waveforms and test circuit.

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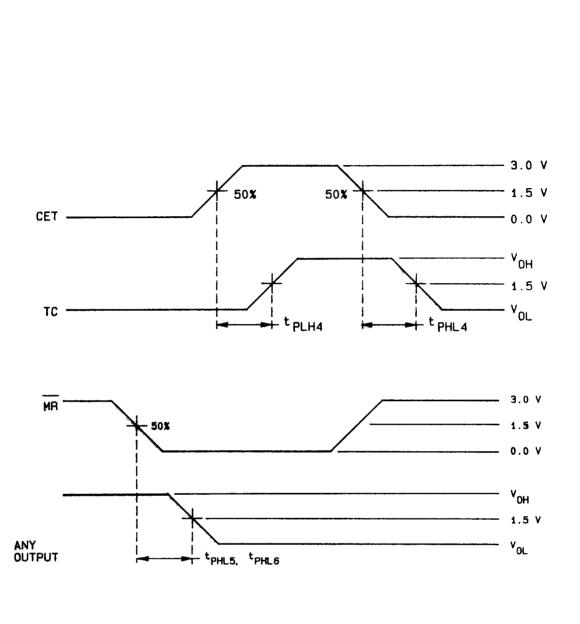


FIGURE 5. Switching waveforms and test circuit - Continued.

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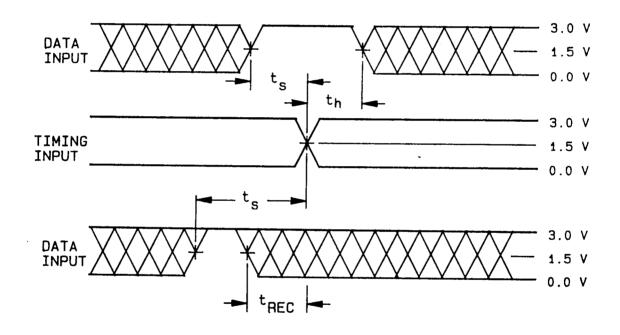


FIGURE 5. Switching waveforms and test circuit - Continued.

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4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

^{*} PDA applies to subgroup 1.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (c_{IN} and c_{OUT} measurements) shall be measured only initial test and after process or design changes which may affect capacitance.
- d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2.

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4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6022.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved sources of supply listed below are for information purposes only and are current only to the date of the last action of this document.

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